

L Number	Hits	Search Text	DB	Time stamp
13	47	(US-6294828-\$ or US-6162660-\$ or US-6130476-\$ or US-6337522-\$ or US-6251766-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-5895976-\$ or US-6425516-\$ or US-6291270-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-5989982-\$ or US-6380061-\$ or US-6281591-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5869899-\$ or US-5933713-\$ or US-6054772-\$ or US-6288335-\$ or US-5824569-\$ or US-5908317-\$ or US-5554887-\$ or US-5641113-\$ or US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6392143-\$ or US-6093972-\$ or US-5895229-\$ or US-5496775-\$ or US-6388333-\$ or US-6469374-\$ or US-6239496-\$ or US-6188127-\$).did.	USPAT	2003/05/30 14:29
40	5	6260264.URPN.	USPAT	2003/05/30 14:36
41	0	6509256.URPN.	USPAT	2003/05/30 14:36
42	5	("5068714" "5128746" "5497938" "5543585" "5751068").PN.	USPAT	2003/05/30 14:36
43	15	("3292240" "3303393" "3517279" "3795047" "4069791" "4157407" "4164005" "4172547" "4234626" "4411980" "4469777" "4572764" "4667401" "4720740" "4868637").PN.	USPAT	2003/05/30 14:39
44	49	5068714.URPN.	USPAT	2003/05/30 14:40
61	5	6168972.URPN.	USPAT	2003/05/30 14:43
62	18	("4676868" "5030799" "5218234" "5355580" "5442240" "5488200" "5543585" "5600180" "5621225" "5641946" "5650667" "5659203" "5703406" "5704116" "5710071" "5751553" "5956605" "6022761").PN.	USPAT	2003/05/30 14:43
75	4	6054772.URPN.	USPAT	2003/05/30 14:52
76	6	("5159434" "5373190" "5496775" "5554887" "5650667" "5777385").PN.	USPAT	2003/05/30 14:52
95	16	("4354911" "4807021" "4827326" "4908689" "5045921" "5103290" "5403776" "5473814" "5579573" "5600180" "5604379" "5703406" "5726500" "5729051" "5757078" "5777391").PN.	USPAT	2003/05/30 14:54
129	1	((silicon adj nitride) near2 adhesive) and ((chip adj (size sized scale) adj package) flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 15:03
130	1	((silicon adj nitride) near2 adhesive) and (solder adj (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 15:04
128	98	(silicon adj nitride) near2 adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 15:08
131	138	(silicon adj nitride) near3 adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 15:09
132	40	((silicon adj nitride) near3 adhesive) not ((silicon adj nitride) near2 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 15:09